

IGBT - Power, Co-PAK N-Channel, Field Stop VII (FS7), SCR, TO247-3L 1200 V, 1.45 V, 40 A AFGHL40T120RWD

Description

Using the novel field stop 7th generation IGBT technology and the Gen7 Diode in TO247 3-lead package, this device offers the optimum performance with low on state voltage and minimal switching losses for both hard and soft switching topologies in automotive applications.

Features

- Extremely Efficient Trench with Field Stop Technology
- Maximum Junction Temperature T_J =175°C
- Short Circuit Rated and Low Saturation Voltage
- Fast Switching and Tightened Parameter Distribution
- AEC-Q101 Qualified, PPAP Available Upon Request
- This Device is Pb–Free, Halogen Free/BFR Free and is RoHS Compliant

Applications

• Automotive E-compressor / Automotive EV PTC Heater / OBC

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

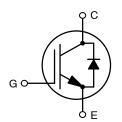
Param	Symbol	Value	Unit	
Collector-to-Emitter Volta	V _{CE}	1200	V	
Gate-to-Emitter Voltage		V_{GE}	±20	
Transient Gate-to-Emitte	er Voltage	1	±30	
Collector Current T _C = 25°C		I _C	80	Α
	T _C = 100°C	1	40	
Power Dissipation	T _C = 25°C	P _D	652	W
	T _C = 100°C		326	
Pulsed Collector Current	$T_C = 25^{\circ}C$, tp = 10 μ s (Note 1)	I _{CM}	120	Α
Diode Forward	T _C = 25°C	I _F	80	
Current	T _C = 100°C		40	
$ \begin{array}{c c} \text{Pulsed Diode Maximum} & T_C = 25^{\circ}\text{C}, \\ \text{Forward Current} & tp = 10~\mu\text{s}~(\text{Note 1}) \end{array} $		I _{FM}	120	
Short Circuit Withstand T V _{GE} = 15 V, V _{CC} = 800 V	T _{SC}	6	μs	
Operating Junction and S Range	T _J , T _{stg}	-55 to +175	°C	
Lead Temperature for So	T _L	260		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1

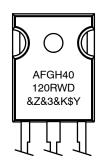
BV _{CES}	V _{CE(sat)} TYP	I _C MAX
1200 V	1.45 V	40 A

PIN CONNECTIONS





MARKING DIAGRAM



AFGH40120RWD = Specific Device Code &Z = Assembly Plant Code &3 = 3-Digit Date Code &K = 2-Digit Lot Traceability Code

\$Y = onsemi Logo

ORDERING INFORMATION

Device	Package	Shipping
AFGHL40T120RWD	TO-247-3L (Pb-Free)	30 Units / Tube

^{1.} Repetitive rating: Pulse width limited by max. junction temperature

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case for IGBT	$R_{ heta JC}$	0.23	°C/W
Thermal Resistance, Junction-to-Case for Diode	$R_{ heta JCD}$	0.41	
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	40	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•			•	•	•
Collector-to-Emitter Breakdown Voltage	BV _{CES}	$V_{GE} = 0 \text{ V}, I_C = 1 \text{ mA}$	1200	-	_	V
Collector-to-Emitter Breakdown Voltage Temperature Coefficient	$\Delta BV_{CES}/\Delta T_{J}$	V_{GE} = 0 V, I_{C} = 9.99 mA	-	1226	-	mV/°C
Zero Gate Voltage Collector Current	I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	-	-	40	μΑ
Gate-to-Emitter Leakage Current	I _{GES}	V _{GE} = ±20 V, V _{CE} = 0 V	-	-	±400	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GE(th)}	$V_{GE} = V_{CE}$, $I_C = 40 \text{ mA}$	4.98	5.88	6.78	V
Collector-to-Emitter Saturation	V _{CE(sat)}	V _{GE} = 15 V, I _C = 40 A, T _J = 25°C	-	1.45	1.78	V
Voltage		V _{GE} = 15 V, I _C = 40 A, T _J = 175°C	-	1.75	_	1
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{IES}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	-	4714	_	pF
Output Capacitance	C _{OES}		-	195	_	1
Reverse Transfer Capacitance	C _{RES}		-	23.7	_	1
Total Gate Charge	Q_{G}	V _{CE} = 600 V, V _{GE} = 15 V, I _C = 40 A	-	170	-	nC
Gate-to-Emitter Charge	Q_{GE}	I _C = 40 A	-	42.2	-]]
Gate-to-Collector Charge	Q_{GC}		-	73.1	-	1
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(on)}	$V_{CE} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, \\ I_{C} = 20 \text{ A}, R_{G} = 4.7 \Omega,$	-	50.1	-	ns
Turn-Off Delay Time	t _{d(off)}	$I_C = 20 \text{ A}, H_G = 4.7 \Omega,$ $T_J = 25^{\circ}\text{C}$	-	293	-	1
Rise Time	t _r		-	30.9	-	1
Fall Time	t _f		-	189	-	1
Turn-On Switching Loss	E _{on}		-	1.37	_	mJ
Turn-Off Switching Loss	E _{off}		-	1.35	_	1
Total Switching Loss	E _{ts}		-	2.72	_	1
Turn-On Delay Time	t _{d(on)}	$V_{CE} = 600 \text{ V}, V_{GE} = 0/15 \text{ V},$	-	55.2	_	ns
Turn-Off Delay Time	t _{d(off)}	$I_C = 40 \text{ A}, R_G = 4.7 \Omega,$ $T_J = 25^{\circ}\text{C}$	-	241	_	1
Rise Time	t _r	-	-	55.2	_	1
Fall Time	t _f		-	122	_	1
Turn-On Switching Loss	E _{on}		_	3.68	_	mJ
Turn-Off Switching Loss	E _{off}		_	1.7	_	1
Total Switching Loss	E _{ts}		_	5.38	_	1

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SWITCHING CHARACTERISTICS			•		•	
Turn-On Delay Time	t _{d(on)}	$V_{CE} = 600 \text{ V}, V_{GE} = 0/15 \text{ V}, \\ I_{C} = 20 \text{ A}, R_{G} = 4.7 \Omega, \\ T_{J} = 175^{\circ}\text{C}$	_	56	_	ns
Turn-Off Delay Time	t _{d(off)}		_	414	-	
Rise Time	t _r	-	_	41.7	-	
Fall Time	t _f		-	375	-]
Turn-On Switching Loss	E _{on}		-	2.13	-	mJ
Turn-Off Switching Loss	E _{off}		-	2.51	-	
Total Switching Loss	E _{ts}		-	4.64	=	
Turn-On Delay Time	t _{d(on)}	$V_{CE} = 600 \text{ V}, V_{GE} = 0/15 \text{ V},$	-	63.1	=	ns
Turn-Off Delay Time	t _{d(off)}	I_C = 40 A, R_G = 4.7 Ω, T_J = 175°C	-	325	=	
Rise Time	t _r		-	71.2	=	
Fall Time	t _f		-	233	=	
Turn-On Switching Loss	E _{on}		-	5.75	=	mJ
Turn-Off Switching Loss	E _{off}		-	3.03	=	
Total Switching Loss	E _{ts}		-	8.79	=	
DIODE CHARACTERISTICS						
Forward Voltage	V _F	I _F = 40 A, T _J = 25°C	-	1.55	1.85	V
		I _F = 40 A, T _J = 175°C	-	1.54	=	
DIODE SWITCHING CHARACTERIS	TICS, INDUCTIVE	LOAD				
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 20 \text{ A},$	-	147	-	ns
Reverse Recovery Charge	Q _{rr}	dl _F /dt = 500 A/μs, T _J = 25°C	-	2110	=	nC
Reverse Recovery Energy	E _{rec}		-	0.53	=	mJ
Peak Reverse Recovery Current	I _{RRM}		-	33.5	-	Α
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 40 \text{ A},$	-	185	-	ns
Reverse Recovery Charge	Q _{rr}	$dI_F/dt = 500 \text{ A/}\mu\text{s}, T_J = 25^{\circ}\text{C}$	_	3612	_	nC
Reverse Recovery Energy	E _{rec}		_	0.78	_	mJ
Peak Reverse Recovery Current	I _{RRM}		-	43.2	-	Α
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 20 \text{ A},$	-	207	-	ns
Reverse Recovery Charge	Q _{rr}	dl _F /dt = 500 A/μs, T _J = 175°C	-	3670	-	nC
Reverse Recovery Energy	E _{rec}		_	1.1	_	mJ
Peak Reverse Recovery Current	I _{RRM}		-	41.5	=	Α
Reverse Recovery Time	t _{rr}	V _R = 600 V, I _F = 40 A,	-	258	-	ns
Reverse Recovery Charge	Q _{rr}	dl _F /dt = 500 A/μs, T _J = 175°C	-	6684	-	nC
Reverse Recovery Energy	E _{rec}		-	1.66	-	mJ
Peak Reverse Recovery Current	I _{RRM}		-	56.5	-	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

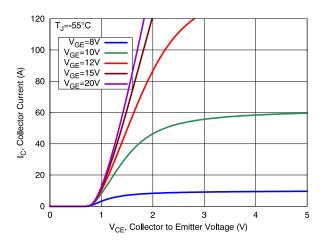


Figure 1. Output Characteristics

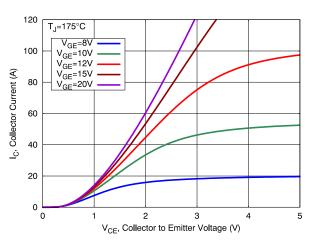


Figure 3. Output Characteristics

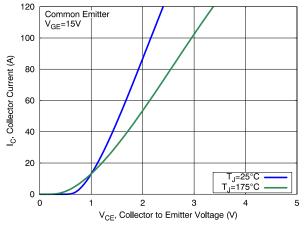


Figure 5. Saturation Characteristics

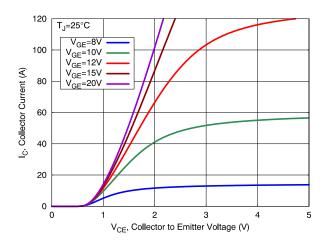


Figure 2. Output Characteristics

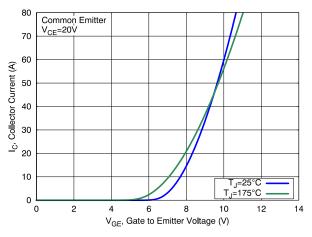


Figure 4. Transfer Characteristics

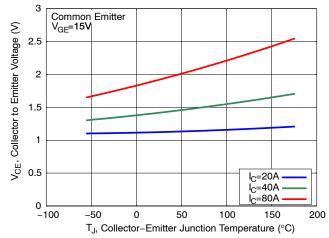


Figure 6. Saturation Voltage vs. Junction Temperature

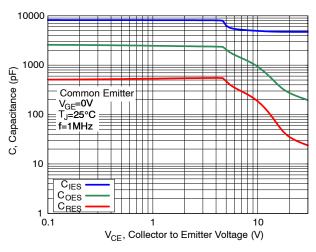


Figure 7. Capacitance Characteristics

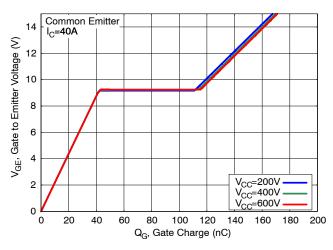


Figure 8. Gate Charge Characteristics

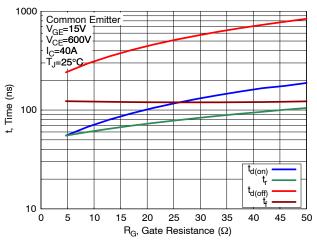


Figure 9. Switching Time vs. Gate Resistance

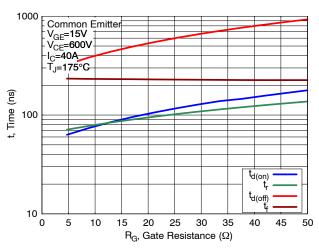


Figure 10. Switching Time vs. Gate Resistance

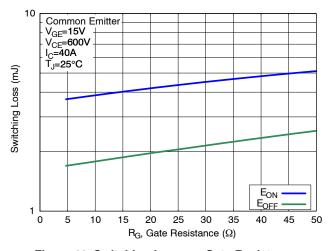


Figure 11. Switching Loss vs. Gate Resistance

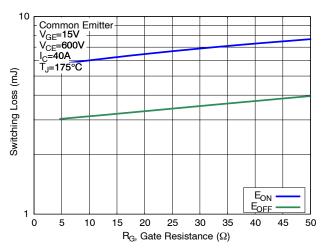


Figure 12. Switching Loss vs. Gate Resistance

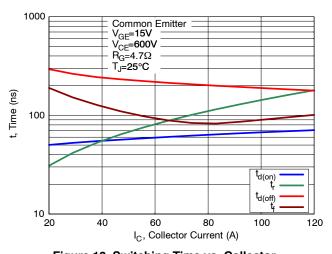


Figure 13. Switching Time vs. Collector Current

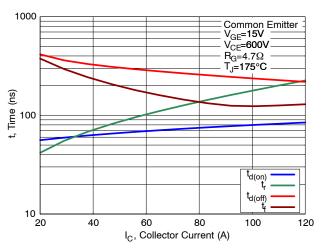


Figure 14. Switching Time vs. Collector Current

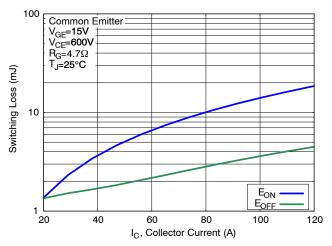


Figure 15. Switching Loss vs. Collector Current

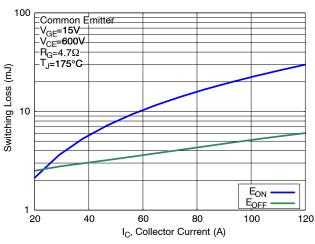


Figure 16. Switching Loss vs. Collector Current

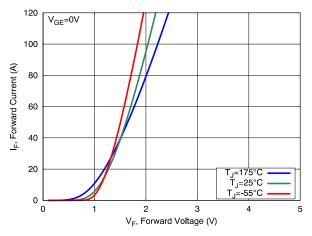


Figure 17. Diode Forward Characteristics

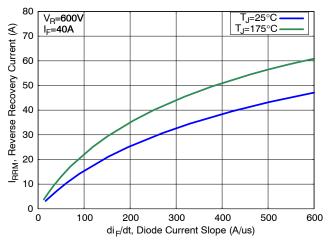
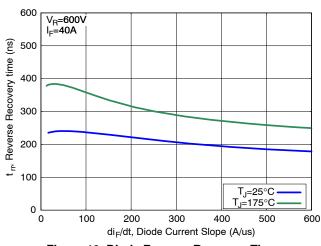


Figure 18. Diode Reverse Recovery Current



10000 V_R=600V I_F=40A Qrr, Reverse Recovery Charge (nC) 8000 6000 4000 2000 T_J=25°C T_J=175°C 100 200 300 400 500 0 600 di_F/dt, Diode Current Slope (A/us)

Figure 19. Diode Reverse Recovery Time

Figure 20. Diode Stored Charge Characteristics

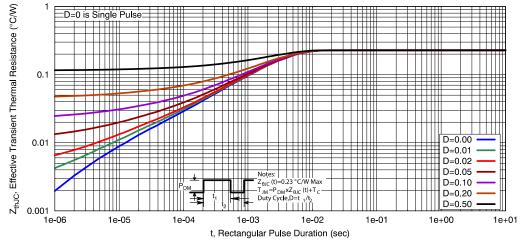


Figure 21. Transient Thermal Impedance of IGBT

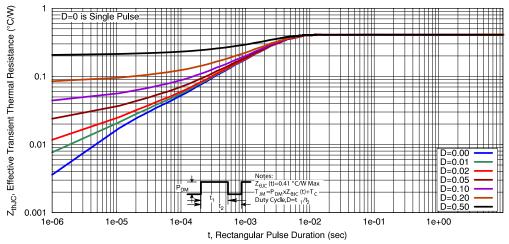
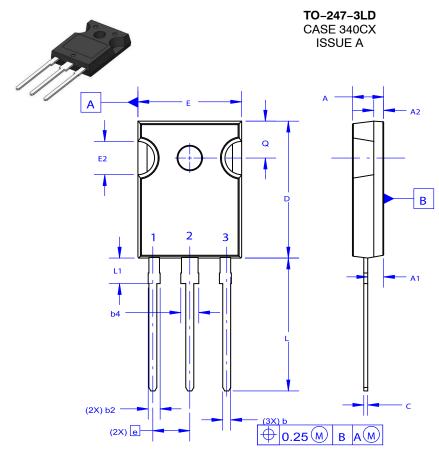


Figure 22. Transient Thermal Impedance of Diode

DATE 06 JUL 2020





NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week

WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

Ø _P —		Φ _{P1} D2
E1 —	2	D1

DIM	MIL	MILLIMETERS				
DIM	MIN	NOM	MAX			
Α	4.58	4.70	4.82			
A 1	2.20	2.40	2.60			
A2	1.40	1.50	1.60			
D	20.32	20.57	20.82			
E	15.37	15.62	15.87			
E2	4.96	5.08	5.20			
е	~	5.56	~			
L	19.75	20.00	20.25			
L1	3.69	3.81	3.93			
ØΡ	3.51	3.58	3.65			
Q	5.34	5.46	5.58			
S	5.34	5.46	5.58			
b	1.17	1.26	1.35			
b2	1.53	1.65	1.77			
b4	2.42	2.54	2.66			
С	0.51	0.61	0.71			
D1	13.08	?	~			
D2	0.51	0.93	1.35			
E1	12.81	~	~			
ØP1	6.60	6.80	7.00			

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